



Soft Silicone Thermal Pad

Description

TH994 is a light grey colored, both side tacky silicone based thermal pad, suitable for use as thermal interface material to dissipate the heat from electronic devices, especially in integrated circuit (IC) and LEDs packaging. This thermal pad has low hardness and flexible, and yet provides very high thermal conductivity, good high temperature resistance and good electrical insulation.

Features

- High thermal conductivity
- Low outgassing
- Flame retardant

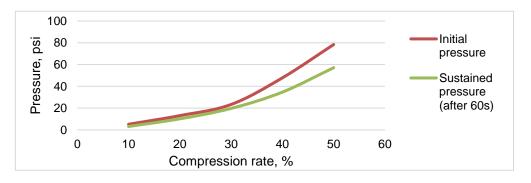
Applications

Thermal conductive interface material for electronic parts and devices.

Cured Properties	Typical Value	Unit	Test Method
Color	Grey	-	PEN 10
Surface tackiness	Natural tack	-	PEN 10
Density	3.3	g/cm ³	PEN 14
Hardness	80	Shore OO	ASTM D2240
Thermal conductivity	8.0	W/mK	ASTM D5470
Thermal resistance			
a) 100kPa	1.93	K-cm ² /W	ASTM D5470-17
b) 300kPa	1.55	K-cm ² /W	ASTM D5470-17
c) 500kPa	1.33	K-cm ² /W	ASTM D5470-17
Tensile strength	1.1	kgf/cm ²	PEN 41
Elongation at break	6.5	%	PEN 41
Breakdown voltage	11.06	kV	PEN 60
Dielectric strength	20.8	kV/mm	PEN 60
Volume resistivity	2.3 x 10 ¹¹	Ohm-cm	PEN 65
Operating temperature	-40 to 200	°C	PEN 92
Volatile content, 30-150°C	0.08	%	PEN 92
Bleed test, 100°C/100hrs	<1.0	mm	PEN 129
Flammability	V-0	-	PEN 55

- * The values above are tested based on batch to batch basis. These values are not use as a basis for preparing specifications.
- * PEN is referring to Penchem standard test method, ASTM is for Test reference only.
- * Specimen dimension for thermal conductivity and thermal resistance measurement 1.0mm thickness, diameter 3.3cm
- * Specimen dimension for tensile and elongation at break test 10cm length x 1cm width x 0.5mm thick
- * PEN 55 UL94 as reference test method

Compression deflection



Revision 06: 30-Sep-2021 (TC)

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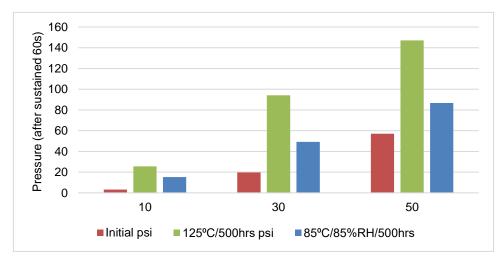


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Compression rate (%)		10	20	30	40	50
Initial pressure	psi	5.20	13.13	23.36	47.80	78.37
Sustained pressure (after 60s)	psi	3.17	10.20	19.73	34.70	57.10

Remark: Specimen dimension: 25mm x 25mm x 1.5mm

Compression deflection after aging test



Compression rate (%)		10	30	50
Initial	psi	3.17	19.73	57.10
125°C/500hrs	psi	25.53	94.13	147.07
85°C/85%RH/500hrs	psi	15.23	49.17	86.73

Remark: Pressure were measured after sustained for 30s. Specimen dimension: 25mm x 25mm x 1.0mm

Guideline of Use

- 1. Pick up silicone thermal pad from release film gently
- 2. Make sure the surface of the substrate is clean and dried before apply the silicone thermal pad
- 3. Position the silicone thermal pad to substrate
- 4. The silicone thermal pad can be applied and removed easily (care must be taken during installation to avoid tearing and contamination).

Storage & Shelf Life

Store the silicone thermal pad in a dried place. Avoid prolong exposure to sunlight.

Shelf life: 3 years

Environment, Health & Safety

This product is intended for industrial use only. For more safety information, please refer to Product Safety Data Sheet (SDS).

Product Dimension

Thickness range: 0.5 to 2.0mm

Other product dimension enquiry, please contact our sales department.

General Information

All right reserved. This information in this document is subjected to change without notice.

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